


Sierra Circuits, Inc.
www.protoexpress.com/hdi

Customer Input			
Part Number/ Rev	: 0001/ 0		
PCB Size in X	: 2 inches X 2 inches		
Number of layers	: 4	PCB Thickness	: 0.062 inches
Material	: 370HR	Outer Layer	: Signal

MicroVias depicted by 		Finished Copper Weight	Finished Thickness (inches)
	SOLDER MASK		0.0005
L-1	TOP SIGNAL	1 Oz	0.0014
	DIELECTRIC		0.0035
L-2	PLANE	1 Oz	0.0014
	DIELECTRIC		0.0470
L-3	PLANE	1 Oz	0.0014
	DIELECTRIC		0.0035
L-4	BOTTOM SIGNAL	1 Oz	0.0014
	SOLDER MASK		0.0005
Total Thickness		0.0606 (inches)	

Customer Saved Impedance Results				
Layer	Impedance Model	Impedance (ohms)	Trace Width (mils)	Space (mils)
Layer 1	Soldermask Coated Microstrip Single-ended	49.99	5.56	--
Layer 4	Soldermask Coated Microstrip Single-ended	49.99	5.56	--

Stackup Details					
Number of Layers	Number of Signal Layers	Number of Sequential Laminations	Number of Plane Layers	Maximum Number of Laser Drills	Mechanical Drills
4	2	0	2	2	1

Technology Parameters and Cost Index					Via Set Information	
PCB TECHNOLOGY LEVELS		Level 1	Level 2	Level 3	Level 4	This stack up supports the following via set
Mechanical Micro via Drill diameter (in mils)		8.00	8.00	7.00	6.00	
Mechanical Micro via Pad diameter (in mils)		16.00	14.00	13.00	12.00	L1-L4
Micro Via Drill Diameter (in mils)		6.00	6.00	6.00	6.00	
Micro Via Pad Diameter (in mils)		14.00	12.00	12.00	12.00	
Trace Width Top Layer (in mils)		5.00	4.50	4.00	4.00	
Trace width Inner Buildup Layers (in mils)		4.50	4.00	3.50	3.00	
Trace Width Inner Core Layers (in mils)		4.50	4.00	3.50	3.00	
Trace Width Bottom Layer (in mils)		5.00	4.50	4.00	4.00	
Cost Index		1.1	1.3	1.7	2.1	